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IN THE U.S. PATENT AND TRADEMARK OFFICE

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Applicant: Shusou WADAKA et al. Conf.: 9099  
Appl. No.: 09/778,872 Group: 2834  
Filed: February 8, 2001 Examiner: Mark O. BUDD  
For: FILM ACOUSTIC WAVE DEVICE AND ITS  
MANUFACTURING METHOD AND CIRCUIT DEVICE

AMENDMENT

Assistant Commissioner for Patents  
Washington, DC 20231

August 23, 2002

Sir:

The following amendments and remarks are respectfully submitted in response to the Office Action dated May 28, 2002, in connection with the above-identified application.

IN THE CLAIMS:

Please amend the claims as follows:

24. (Once Amended) A wafer having a plurality of acoustic wave devices formed thereon and exhibiting common operational characteristics, each of said acoustical wave devices manufactured according to a method comprising:

(a) forming a ground electrode on the wafer which is intended to be placed on top of a semiconductor substrate;